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(12) **United States Design Patent** (10) **Patent No.:** **US D885,444 S**  
**Tsuji** (45) **Date of Patent:** **\*\* May 26, 2020**

(54) **SEAL MEMBER FOR USE IN SEMICONDUCTOR PRODUCTION APPARATUS**

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(73) Assignee: **Valqua, Ltd.**, Tokyo (JP)

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**  
USPC ..... **D15/7**  
CPC ..... **F16K 51/02** (2013.01)

(58) **Field of Classification Search**

USPC ..... D15/7, 9, 11, 17, 21, 28, 123, 199;  
D23/269, 386, 259; D8/349;  
277/602-626; 285/95, 109, 336, 910, 918  
CPC ..... F16K 51/02; F16J 15/025; F16J 15/0887;  
F16J 15/104; F16J 15/128

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for seal member for use in semiconductor production apparatus, as shown and described.

**DESCRIPTION**

**1.1** is a perspective view of a seal member for use in semiconductor production apparatus, showing my new design;

**1.2** is a front elevation view thereof;

**1.3** is a rear elevation view thereof;

**1.4** is a left side elevation view thereof;

**1.5** is a right side elevation view thereof;

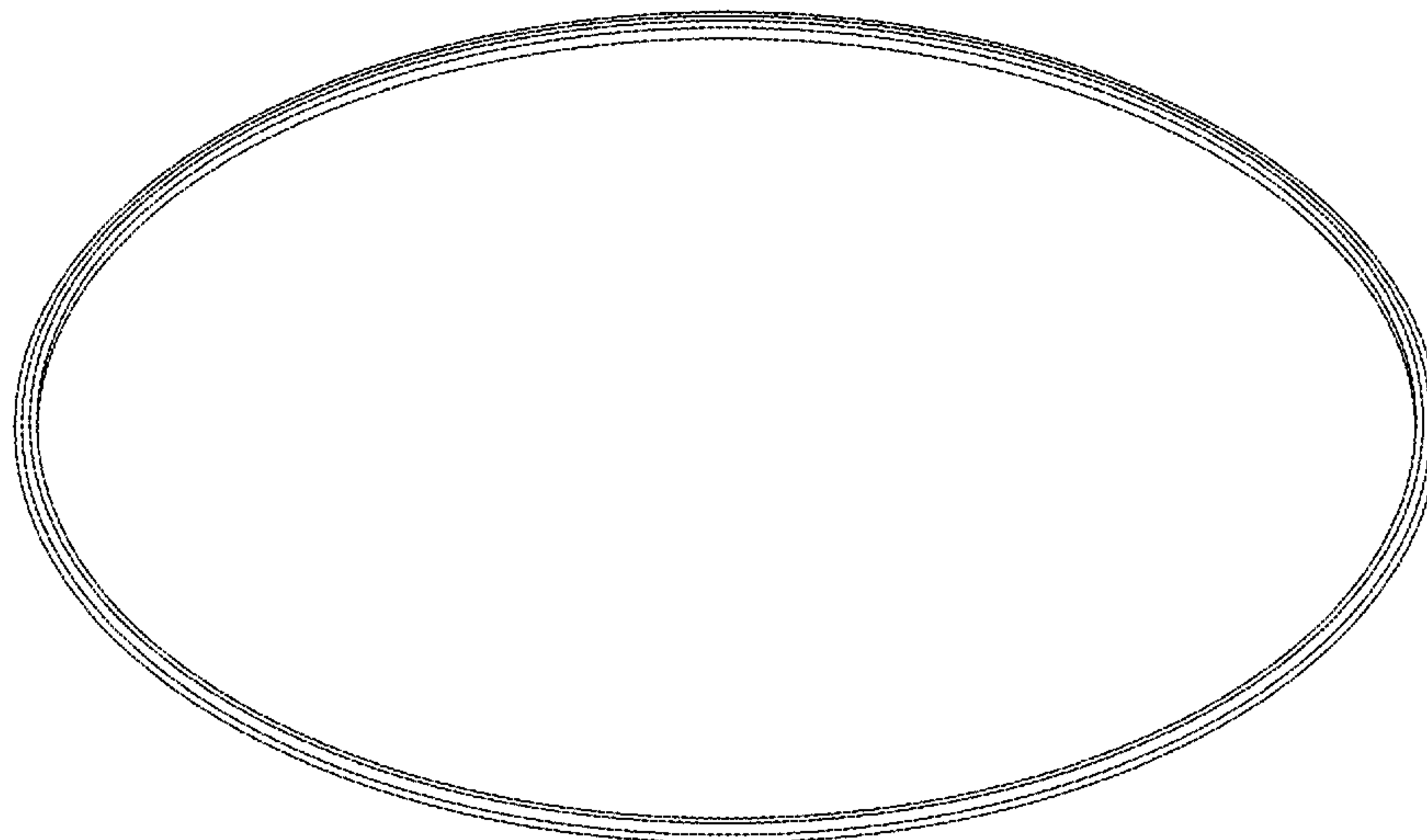
**1.6** is a top view thereof;

**1.7** is a bottom view thereof;

**1.8** is a cross-sectional view thereof taken along lines **1.8-1.8** shown in **Reproduction 1.6**; and

**1.9** is an enlarged cross-sectional view of a portion thereof taken from area **1.9** shown in **Reproduction 1.8**.

**1 Claim, 9 Drawing Sheets**



(56)

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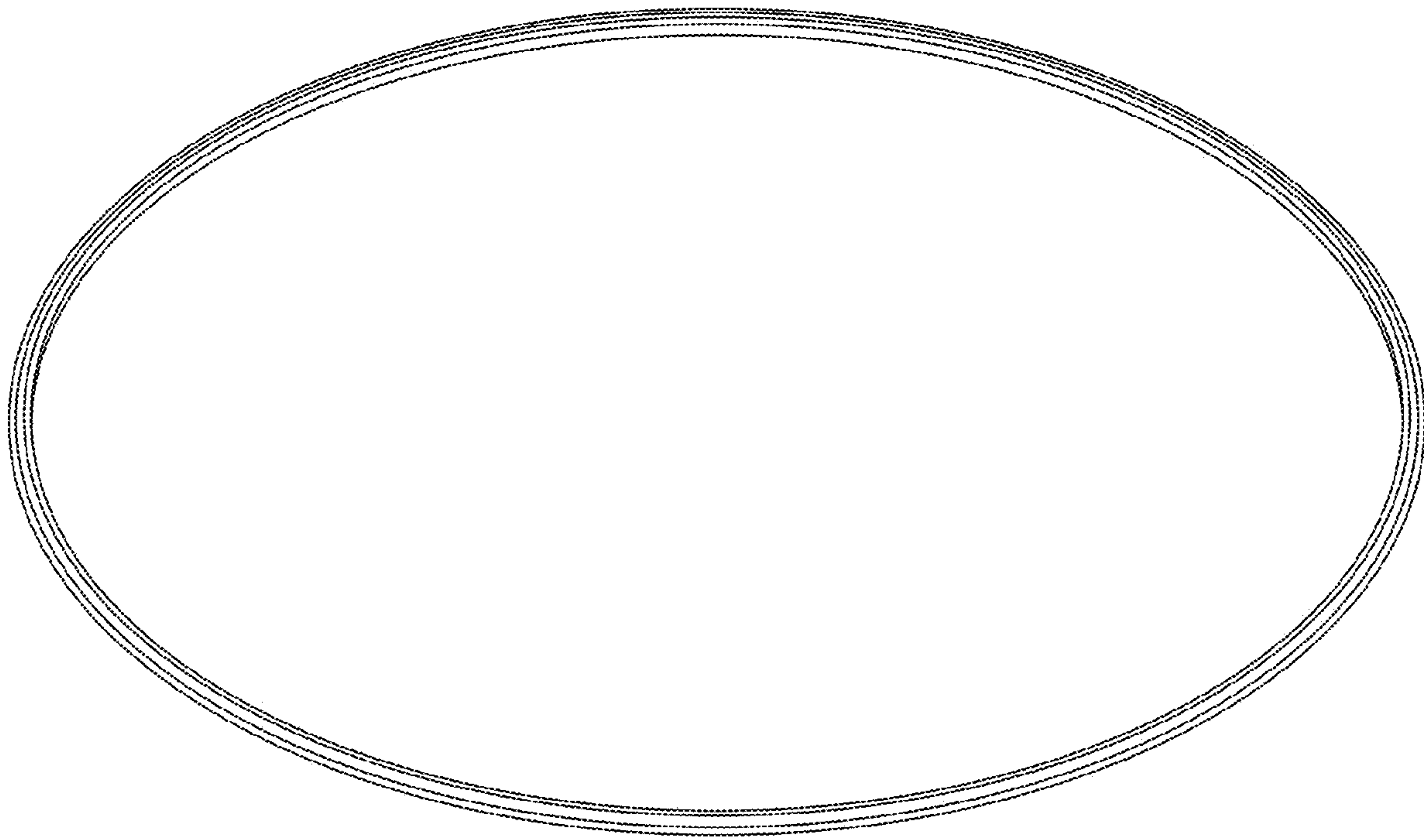
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1.1



**1.2**

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**1.3**

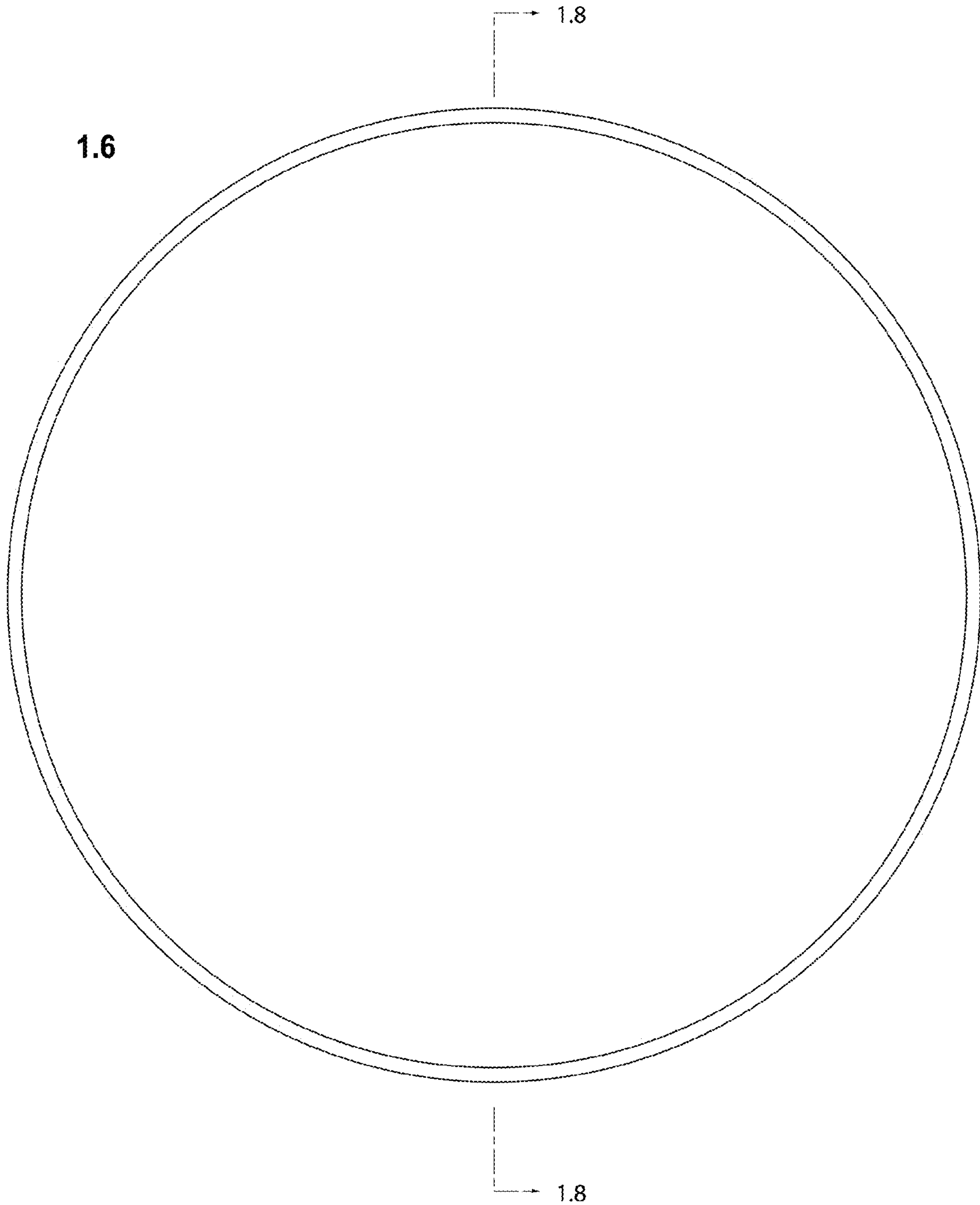
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**1.4**

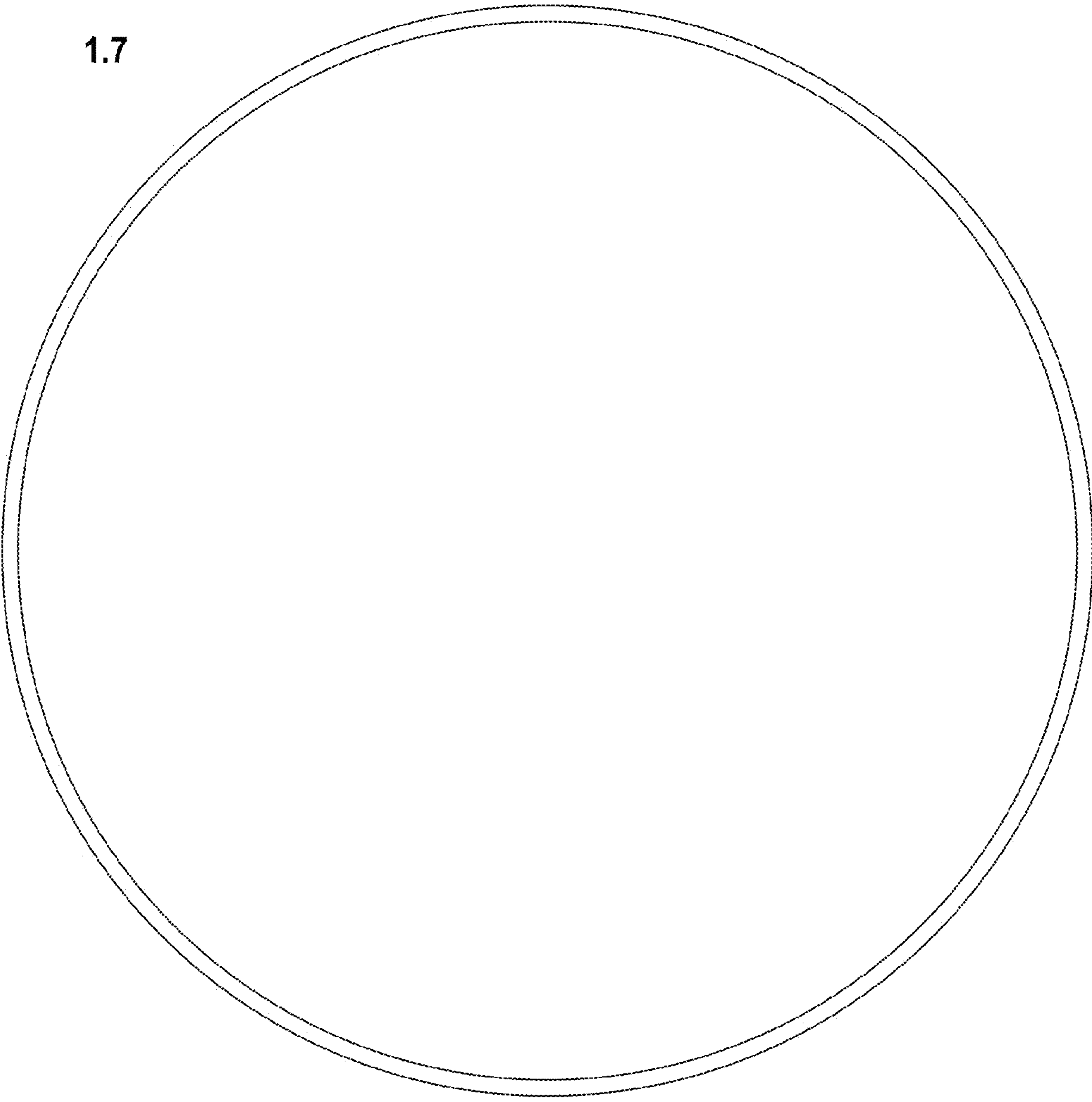
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**1.5**

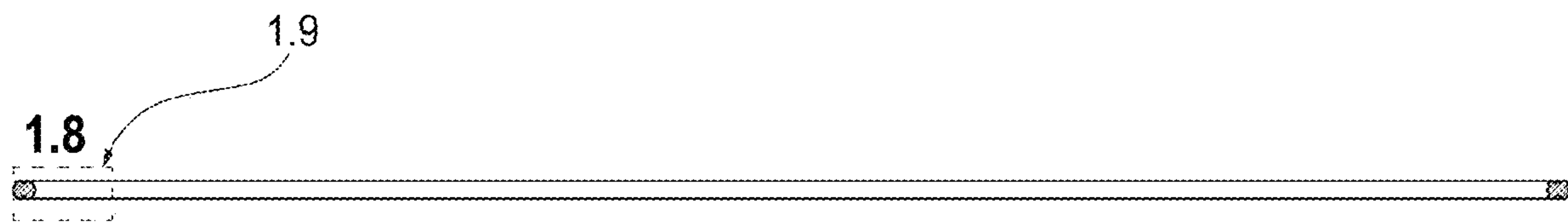
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1.7



1.9

